



LIPTAI

MSL240R50C

## MOSFETs Silicon 500V N-Channel MOS

### ■ Applications

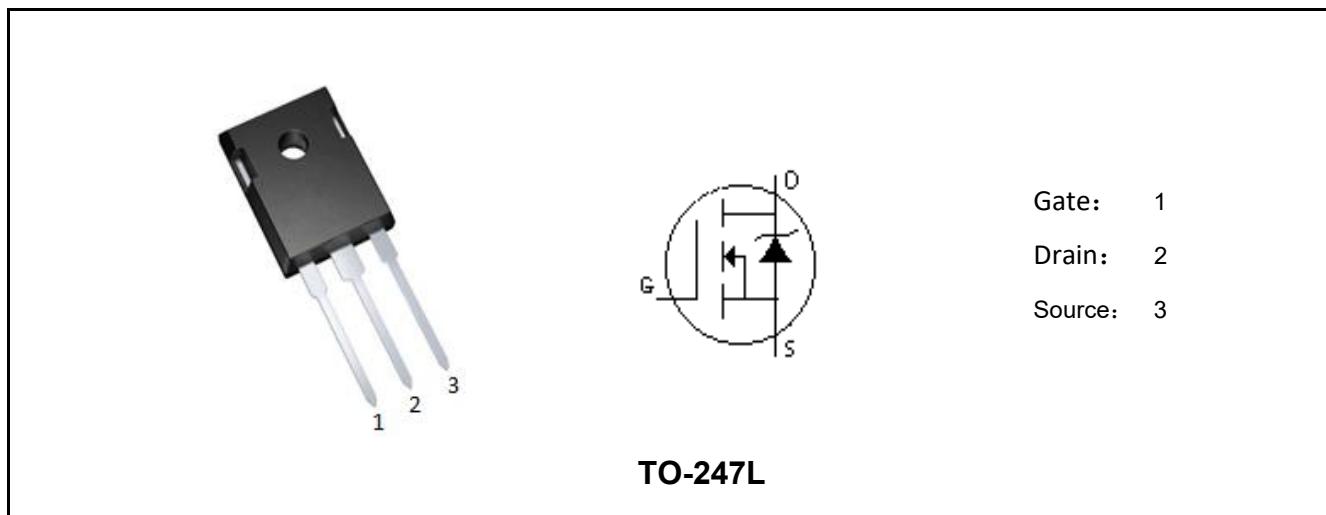
- Power factor correction (PFC)
- Switched mode power supplies(SMPS)
- Uninterruptible Power Supply (UPS)

### ■ Features

- Multi-Epi process SJ-FET
- Low  $R_{DS(ON)}$
- Ultra Low Gate Charge
- RoHS and Halogen-Free Compliant
- 100% UIS and RG Tested

### ■ Product Summary

$V_{DS}$ @ $T_{j,max}$	550	V
$I_D$	18	A
$R_{DS(ON),Typ}@10V$	0.2	$\Omega$
$Q_g$	20	nC



Marking	Package	Packaging	Min. package quantity
MSL240R50C	TO-247L	Tube	450



**■ Absolute Maximum Ratings (T<sub>c</sub>=25°C unless otherwise noted)**

Parameter	Symbol	Ratings	Unit
Drain-Source Voltage	V <sub>DS</sub>	500	V
Gate-Source Voltage	V <sub>GS</sub>	±30	V
Continuous Drain Current T <sub>c</sub> =25°C (Note 1)	I <sub>D</sub>	18	A
Continuous Drain Current T <sub>c</sub> =100°C (Note 1)		11	
Drain Current-Pulsed (Note 1)	I <sub>DM</sub>	43	A
Total Dissipation	P <sub>D</sub>	138	W
Junction Temperature	T <sub>j</sub>	150	°C
Storage Temperature	T <sub>stg</sub>	-55-150	°C
Single Pulse Avalanche Energy (Note 2)	E <sub>AS</sub>	284	mJ

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

**■ Thermal Characteristics**

Parameter	Symbol	Max	Unit
Maximum Junction-to-Case	R <sub>θJC</sub>	0.9	°C/W
Maximum Junction-to-Ambient	R <sub>θJA</sub>	60	°C/W

Note 1: Ensure that the channel temperature does not exceed 150°C.

Note 2: V<sub>DD</sub>=50V, T<sub>ch</sub>= 25°C(initial), I<sub>AS</sub>=18A, R<sub>g</sub>=25Ω.

Note: This transistor is sensitive to electrostatic discharge and should be handled with care.





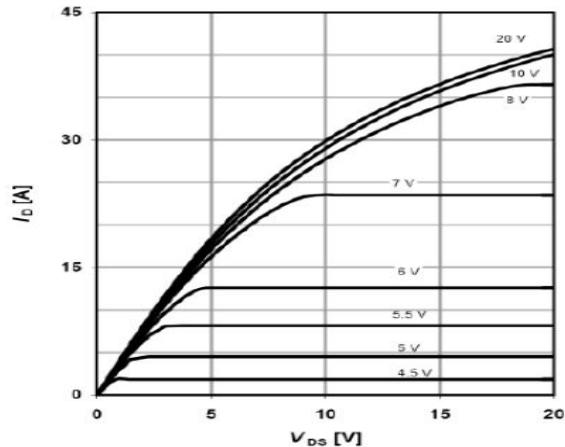
■ Electrical Characteristics (T<sub>c</sub>=25°C unless otherwise noted)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
<b>Static Parameters</b>						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V, I <sub>D</sub> =250uA	500	-	-	V
		T <sub>j</sub> =150°C	550	-	-	
Drain-Source Leakage Current	I <sub>DSS</sub>	V <sub>DS</sub> =500V, V <sub>GS</sub> =0V	-	-	1	uA
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±30V, V <sub>DS</sub> =0V	-	-	±100	nA
Gate Threshold Voltage	V <sub>GS(TH)</sub>	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =250uA	2.5	3.5	4.5	V
Drain-Source On Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =9A	-	0.2	0.24	Ω
		T <sub>j</sub> =150°C	-	0.54	-	
<b>Dynamic Characteristics</b>						
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> =25V, V <sub>GS</sub> =0V, f=1.0MHz	-	815	-	pF
Output Capacitance	C <sub>oss</sub>		-	350	-	pF
Reverse Transfer Capacitance	C <sub>rss</sub>		-	10	-	pF
Gate Resistance	R <sub>g</sub>	V <sub>DS</sub> =0V, V <sub>GS</sub> =0V, f=1.0MHz	-	3.8	-	Ω
<b>Switching Paramters</b>						
Turn-On Delay Time	t <sub>d(on)</sub>	V <sub>DS</sub> =400V, I <sub>D</sub> =9A, V <sub>GS</sub> =10V, R <sub>G</sub> =25Ω	-	13	-	ns
Turn-On Rise Time	t <sub>r</sub>		-	12	-	ns
Turn-Off Delay Time	t <sub>d(off)</sub>		-	100	-	ns
Turn-Off Fall Time	t <sub>f</sub>		-	12	-	ns
Total Gate Charge	Q <sub>g</sub>	V <sub>DS</sub> =400V, I <sub>D</sub> =9A, V <sub>GS</sub> =10V	-	20	-	nC
Gate-Source Charge	Q <sub>gs</sub>		-	5	-	nC
Gate-Drain Charge	Q <sub>gd</sub>		-	7.5	-	nC
<b>Source-Drain Characteristics</b>						
Max. Diode Forward Cuurent	I <sub>S</sub>		-	-	18	A
Max. Pulsed Forward Cuurent	I <sub>SM</sub>		-	-	43	A
Diode Forward Voltage	V <sub>sd</sub>	V <sub>GS</sub> =0V, I <sub>S</sub> =9A	-	0.9	1.5	V
Reverse Recovery Time	t <sub>rr</sub>	V <sub>R</sub> =400V, I <sub>F</sub> =9A, di/dt=100A/us	-	340	-	ns
Reverse Recovery Charge	Q <sub>rr</sub>		-	4.5	-	μC

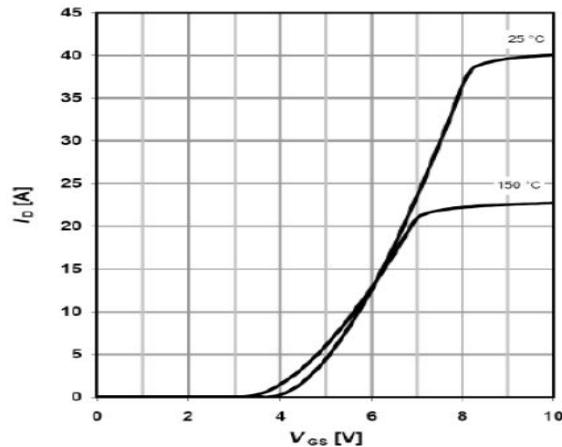




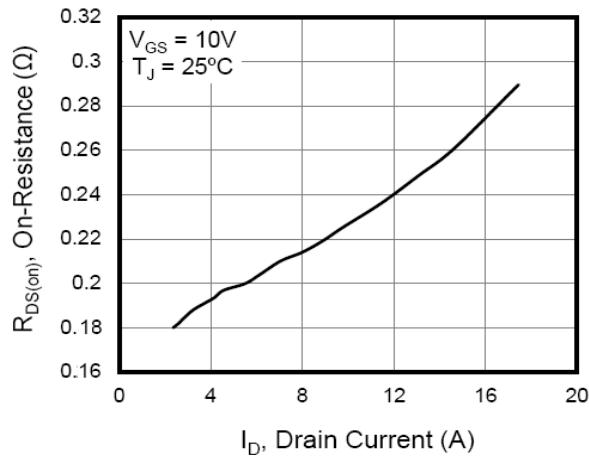
## ■ Characteristics Curves



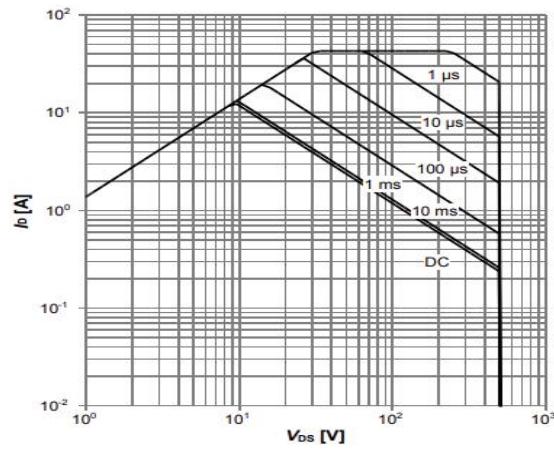
Output Characteristics



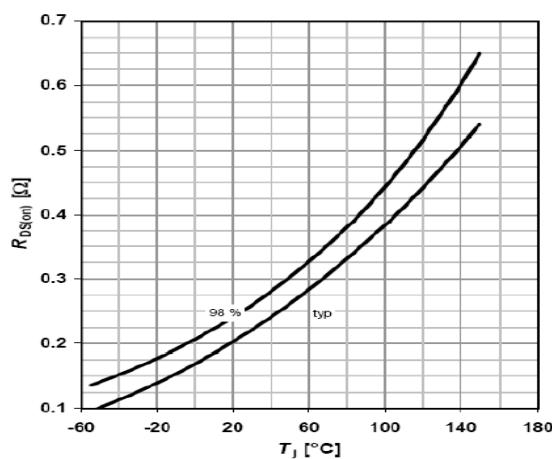
Transfer Characteristics



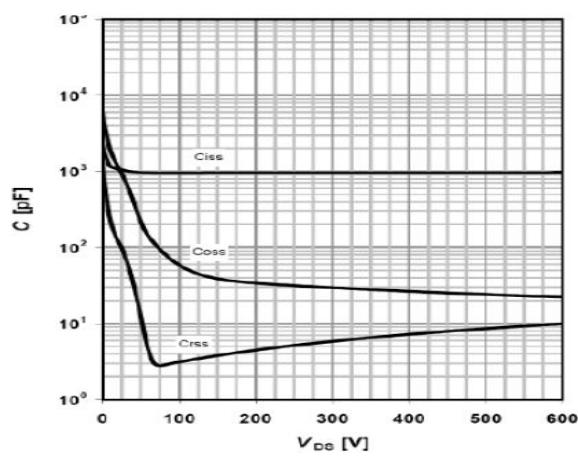
On Resistance Vs Drain Current



Maximum Safe Operating Area



Rdson-JunctionTemperature



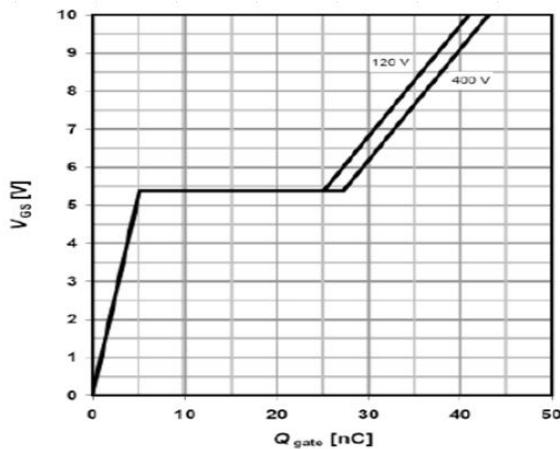
Capacitance



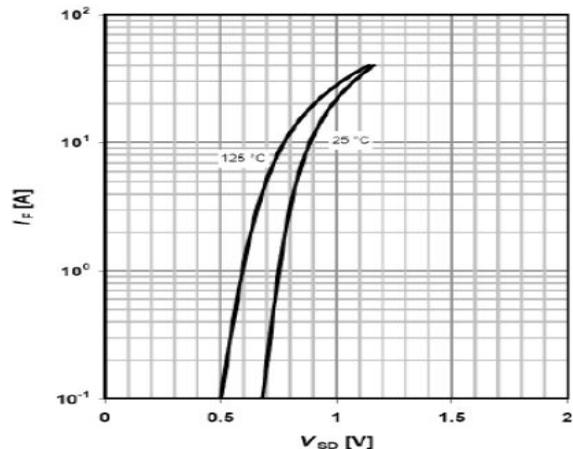


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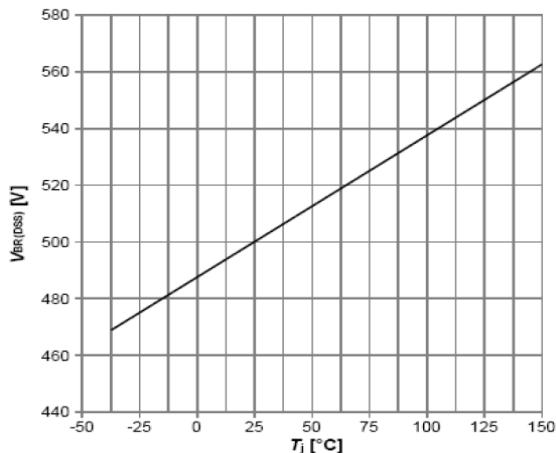
**MSL240R50C**



**Gate Charge Waveform**



**Source-Drain Diode Forward Voltage**



**Breakdown Voltage Vs Junction Temperature**

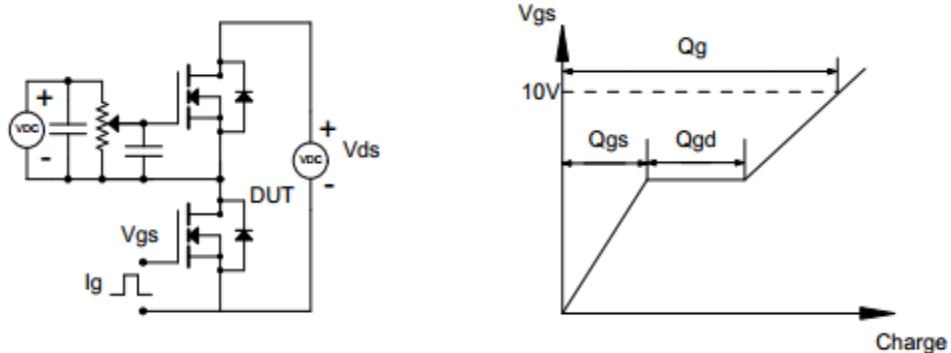
Note : The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.



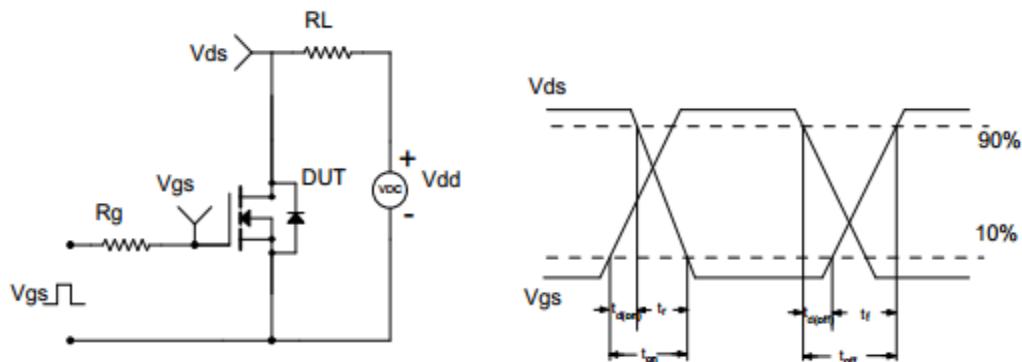


## ■ Test Circuit & Waveform

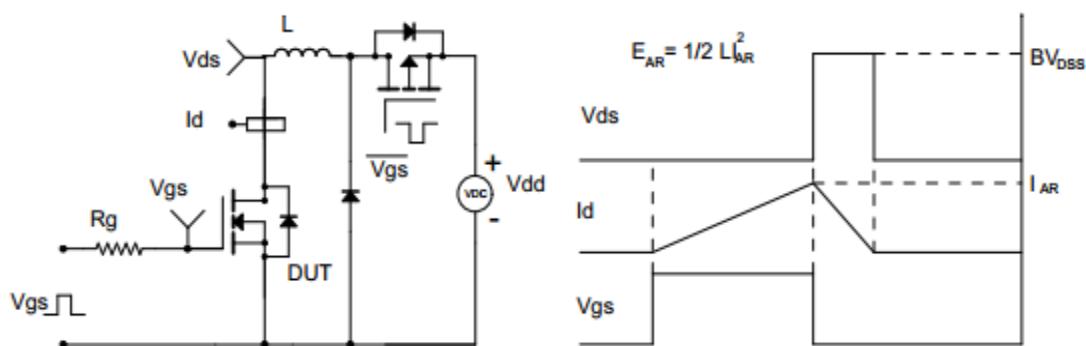
Gate Charge Test Circuit & Waveform



Resistive Switching Test Circuit & Waveform



Unclamped Inductive Switching (UIS) Test Circuit & Waveform





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## ■ TO-247L Package Dimensions

Unit: mm

Symbol	Min	Nom	Max	Symbol	Min	Nom	Max
A	4.80		5.20	E1	13.00		13.60
A1	2.20	2.40	2.60	E2	5.00		5.50
A2	1.85		2.15	E3	1.90		2.60
b	1.07		1.33	e		5.44	
b2	1.90		2.16	L	19.30		19.90
b4	2.90		3.20	L1	3.75	3.95	4.15
c	0.52		0.68	ΦP	3.40		3.80
D	20.70		21.30	ΦP1	7.00		7.40
D1	16.15		16.95	S	6.04	6.15	6.30
E	15.50		16.10				

